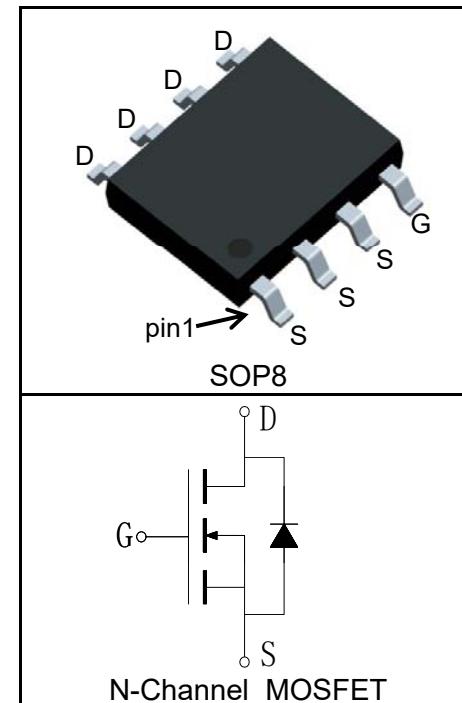


## Features

- 20V/12A,
- $R_{DS\ (ON)} = 7.5\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 10\text{V}$
- $R_{DS\ (ON)} = 8\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 4.5\text{V}$
- $R_{DS\ (ON)} = 10\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 2.5\text{V}$
- Low  $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

## Pin Description



## Applications

- Power Management
- Battery Protection



Halogen-Free

## Absolute Maximum Ratings

| Symbol   | Parameter   | Rating                   | Unit               |
|--|---|--------------------------|--------------------|
| <b>Common Ratings</b> ( $T_A = 25^\circ\text{C}$ Unless Otherwise Noted) |   |                          |                    |
| $V_{DSS}$  | Drain-Source Voltage                                | 20                       | V                  |
| $V_{GSS}$  | Gate-Source Voltage                                 | $\pm 12$                 |                    |
| $T_J$  | Maximum Junction Temperature                        | 150                      | $^\circ\text{C}$   |
| $T_{STG}$  | Storage Temperature Range                           | -55 to 150               | $^\circ\text{C}$   |
| $I_S$  | Diode Continuous Forward Current                    | $T_A = 25^\circ\text{C}$ | A                  |
| <b>Mounted on Large Heat Sink</b>  |   |                          |                    |
| $I_{DP}^{(1)}$   | 300 $\mu\text{s}$ Pulse Drain Current Tested        | $T_A = 25^\circ\text{C}$ | 48                 |
| $I_D^{(2)}$  | Continuous Drain Current ( $V_{GS} = 4.5\text{V}$ ) | $T_A = 25^\circ\text{C}$ | 12                 |
|  |   | $T_A = 70^\circ\text{C}$ | 9.6                |
| $P_D$  | Maximum Power Dissipation                           | $T_A = 25^\circ\text{C}$ | 2.5                |
|  |   | $T_A = 70^\circ\text{C}$ | 1.6                |
| $R_{\theta JC}$  | Thermal Resistance-Junction to Case                 | -                        | $^\circ\text{C/W}$ |
| $R_{\theta JA}^{(3)}$  | Thermal Resistance-Junction to Ambient              | 50                       | $^\circ\text{C/W}$ |
| <b>Drain-Source Avalanche Ratings</b>                                    |   |                          |                    |
| $E_{AS}^{(4)}$   | Avalanche Energy, Single Pulsed                     | 45                       | mJ                 |

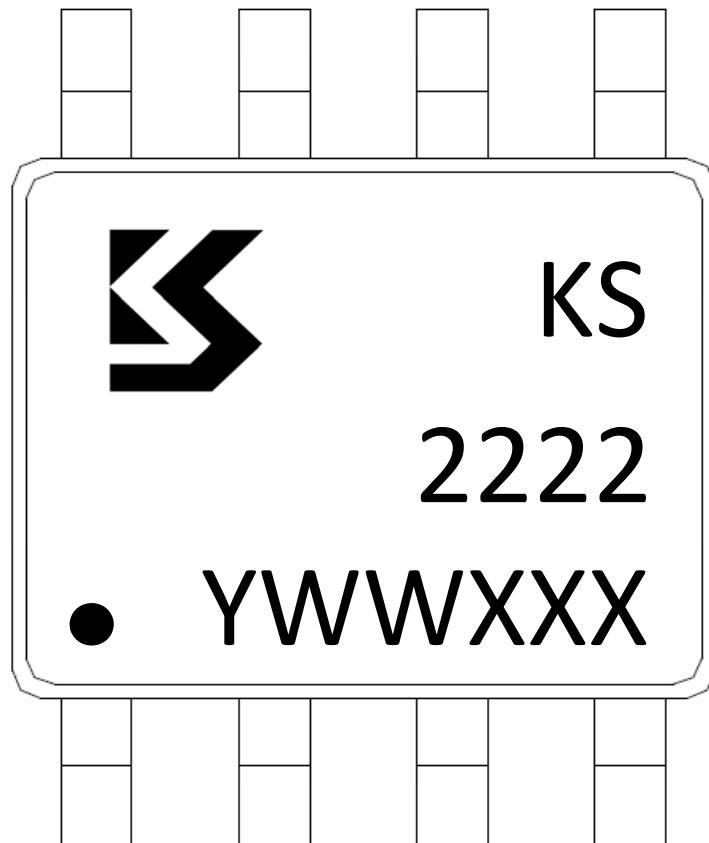
**Electrical Characteristics (T<sub>A</sub>=25°C Unless Otherwise Noted)**

| Symbol  | Parameter                        | Test Condition  | KS2222HA |      |      | Unit |
|---|----------------------------------|---|----------|------|------|------|
|   |                                  |   | Min.     | Typ. | Max. |      |
| <b>Static Characteristics</b>                   |                                  |   |          |      |      |      |
| BV <sub>DSS</sub>                               | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA   | 20       |      |      | V    |
| I <sub>DSS</sub>                                | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V   |          |      | 1    | μA   |
|   |                                  | T <sub>J</sub> =125°C   |          |      | 30   |      |
| V <sub>GS(th)</sub>                             | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA                                 | 0.4      | 0.7  | 1    | V    |
| I <sub>GSS</sub>                                | Gate Leakage Current             | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V  |          |      | ±100 | nA   |
| R <sub>DS(ON)</sub> <sup>⑤</sup>                | Drain-Source On-state Resistance | V <sub>GS</sub> =10V, I <sub>DS</sub> =10A  |          | 7.5  | 9    | mΩ   |
|   |                                  | V <sub>GS</sub> =4.5V, I <sub>DS</sub> =8A  |          | 8    | 11   | mΩ   |
|   |                                  | V <sub>GS</sub> =2.5V, I <sub>DS</sub> =4A  |          | 10   | 15   | mΩ   |
| <b>Diode Characteristics</b>                    |                                  |   |          |      |      |      |
| V <sub>SD</sub> <sup>⑤</sup>                    | Diode Forward Voltage            | I <sub>SD</sub> =10A, V <sub>GS</sub> =0V   |          | 0.85 | 1.2  | V    |
| t <sub>rr</sub>                                 | Reverse Recovery Time            | I <sub>SD</sub> =10A, dI <sub>SD</sub> /dt=100A/μs  |          | 13   |      | ns   |
| Q <sub>rr</sub>                                 | Reverse Recovery Charge          |   |          | 17   |      | nC   |
| <b>Dynamic Characteristics</b> <sup>⑥</sup>     |                                  |   |          |      |      |      |
| R <sub>G</sub>                                  | Gate Resistance                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz  |          | 2.5  |      | Ω    |
| C <sub>iss</sub>                                | Input Capacitance                | V <sub>GS</sub> =0V,<br>V <sub>DS</sub> =10V,<br>Frequency=1.0MHz                         |          | 1290 |      | pF   |
| C <sub>oss</sub>                                | Output Capacitance               |   |          | 200  |      |      |
| C <sub>rss</sub>                                | Reverse Transfer Capacitance     |   |          | 180  |      |      |
| t <sub>d(ON)</sub>                              | Turn-on Delay Time               | V <sub>DD</sub> =10V, I <sub>DS</sub> =10A,<br>V <sub>GEN</sub> =4.5V, R <sub>G</sub> =3Ω |          | 3.1  |      | ns   |
| t <sub>r</sub>                                  | Turn-on Rise Time                |   |          | 4.6  |      |      |
| t <sub>d(OFF)</sub>                             | Turn-off Delay Time              |   |          | 9    |      |      |
| t <sub>f</sub>                                  | Turn-off Fall Time               |   |          | 9.4  |      |      |
| <b>Gate Charge Characteristics</b> <sup>⑥</sup> |                                  |   |          |      |      |      |
| Q <sub>g</sub>                                  | Total Gate Charge                | V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V,<br>I <sub>DS</sub> =10A                      |          | 18   |      | nC   |
| Q <sub>gs</sub>                                 | Gate-Source Charge               |   |          | 7.5  |      |      |
| Q <sub>gd</sub>                                 | Gate-Drain Charge                |   |          | 8.5  |      |      |

- Notes:
- ①Pulse width limited by safe operating area.
  - ②Calculated continuous current based on maximum allowable junction temperature.
  - ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
  - ④Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.1mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 30A, V<sub>GS</sub> = 10V.
  - ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
  - ⑥Guaranteed by design, not subject to production testing.

**Ordering and Marking Information**

| Device   | Package | Packaging | Quantity | Reel Size | Tape width |
|----------|---------|-----------|----------|-----------|------------|
| KS2222HA | SOP8    | Tape&Reel | 3000     | 13"       | 12mm       |

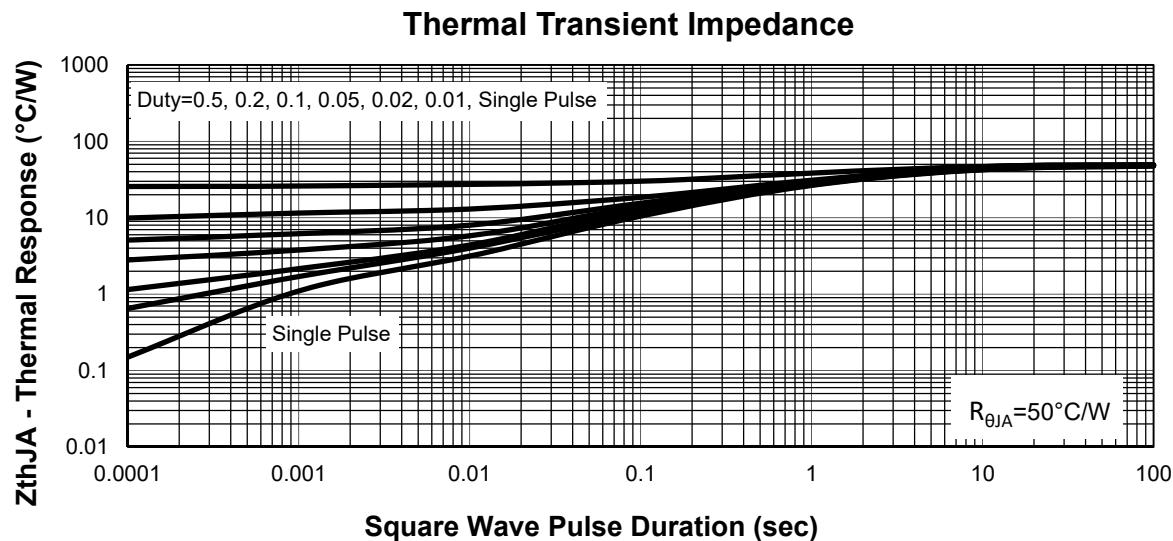
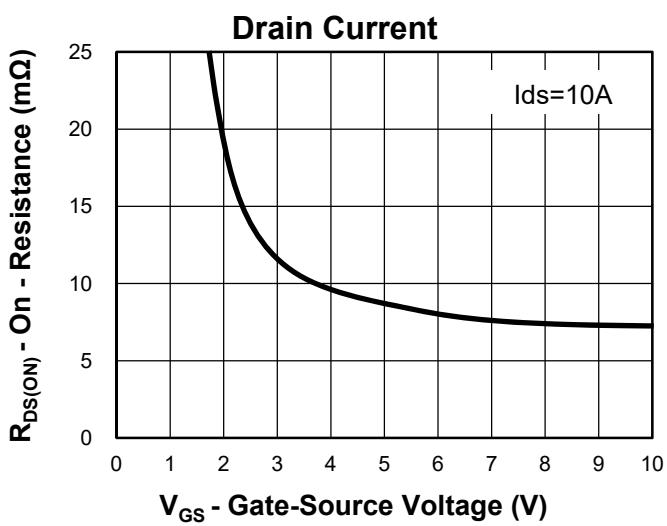
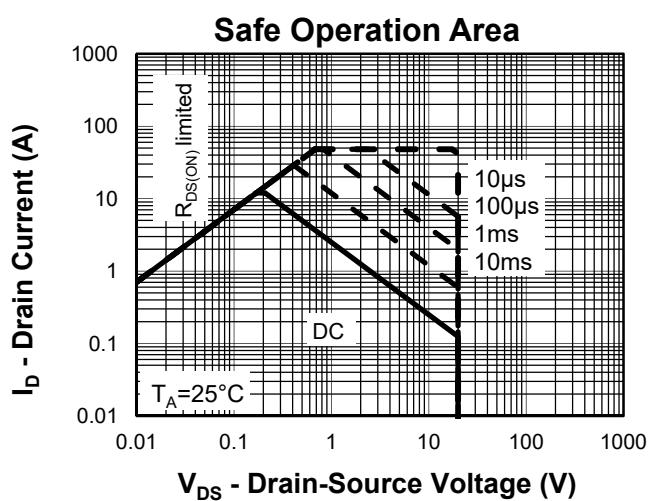
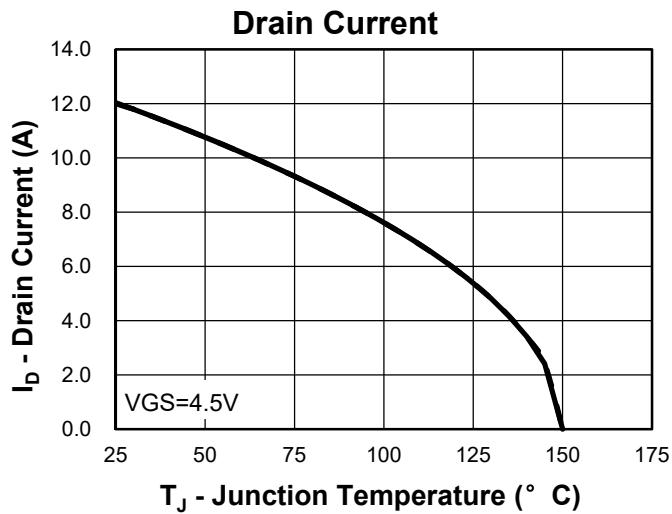
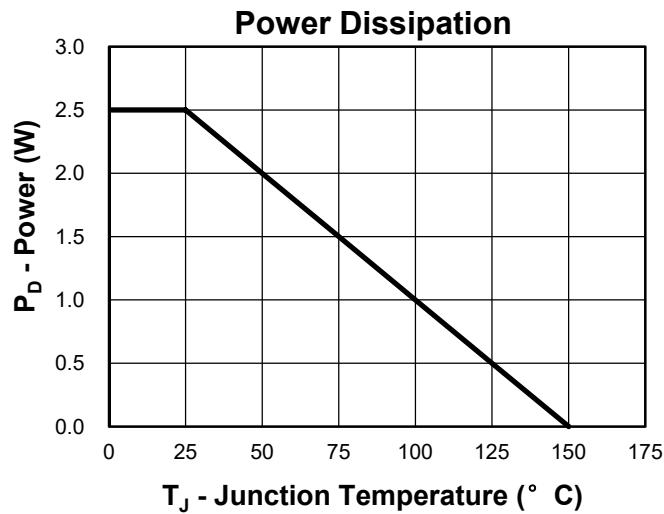


Y =Year,2017-A,2018-B,etc.

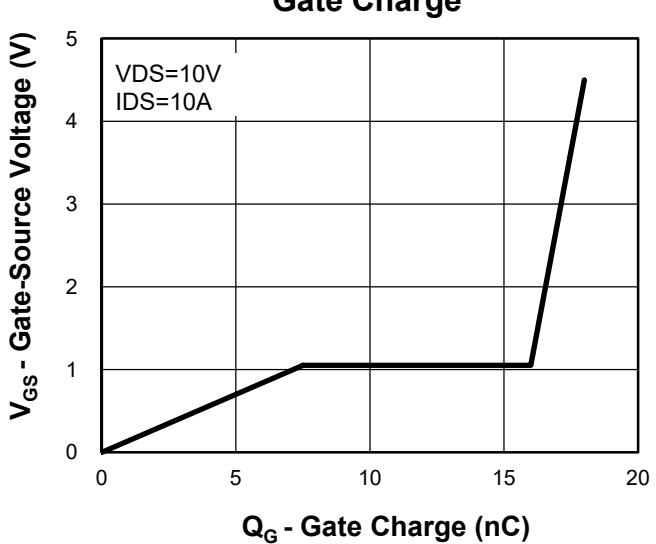
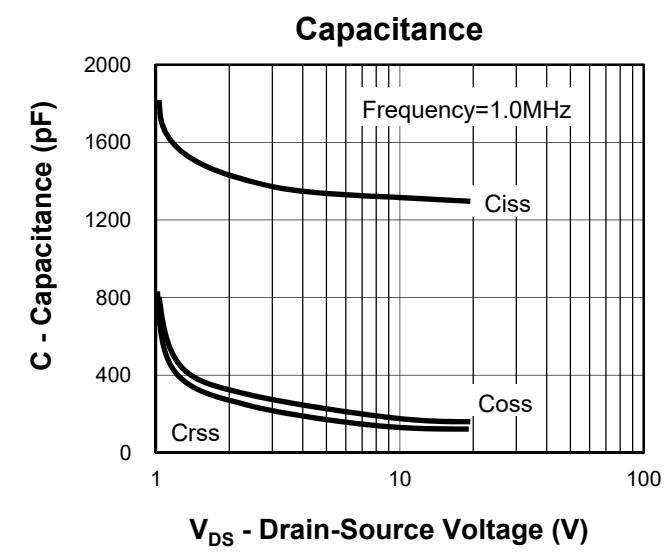
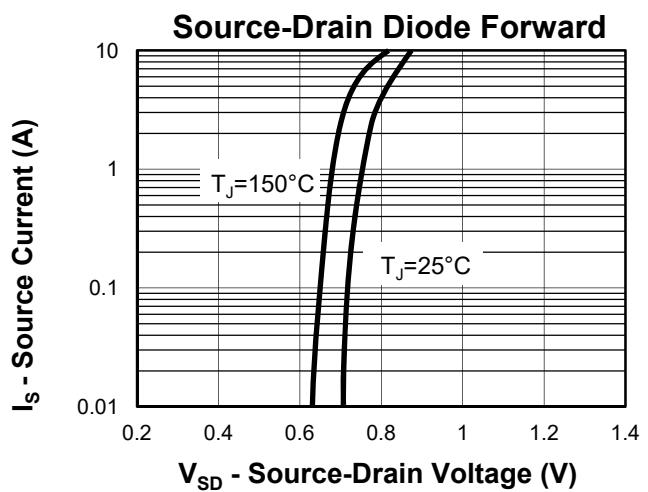
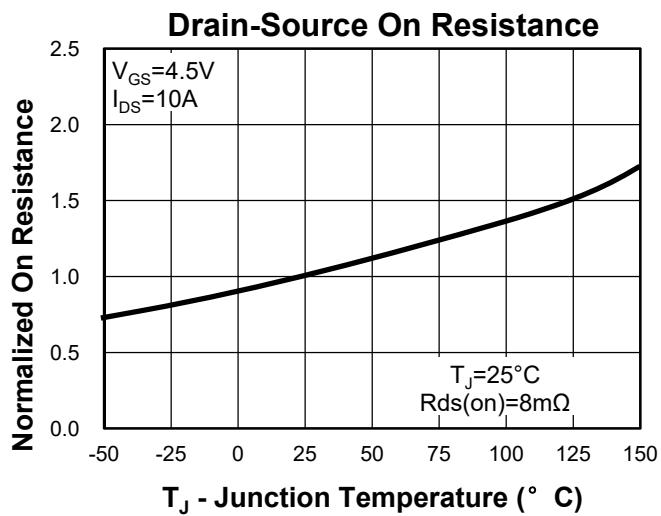
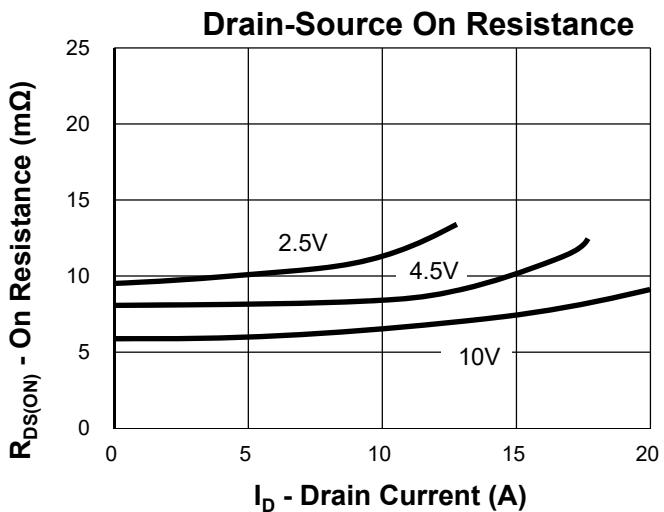
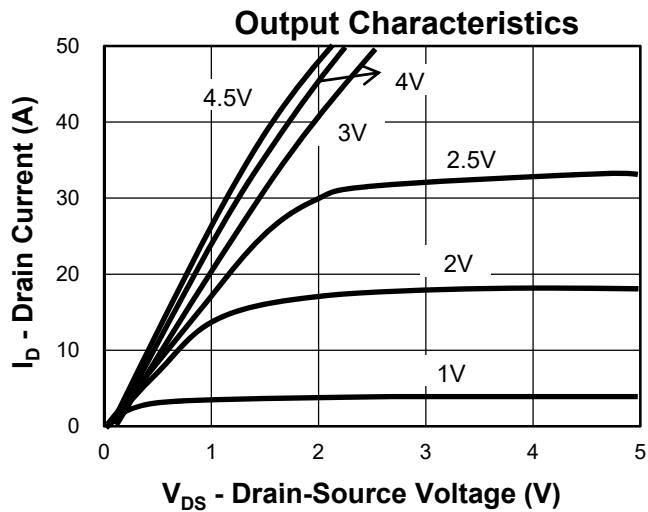
WW =Week.

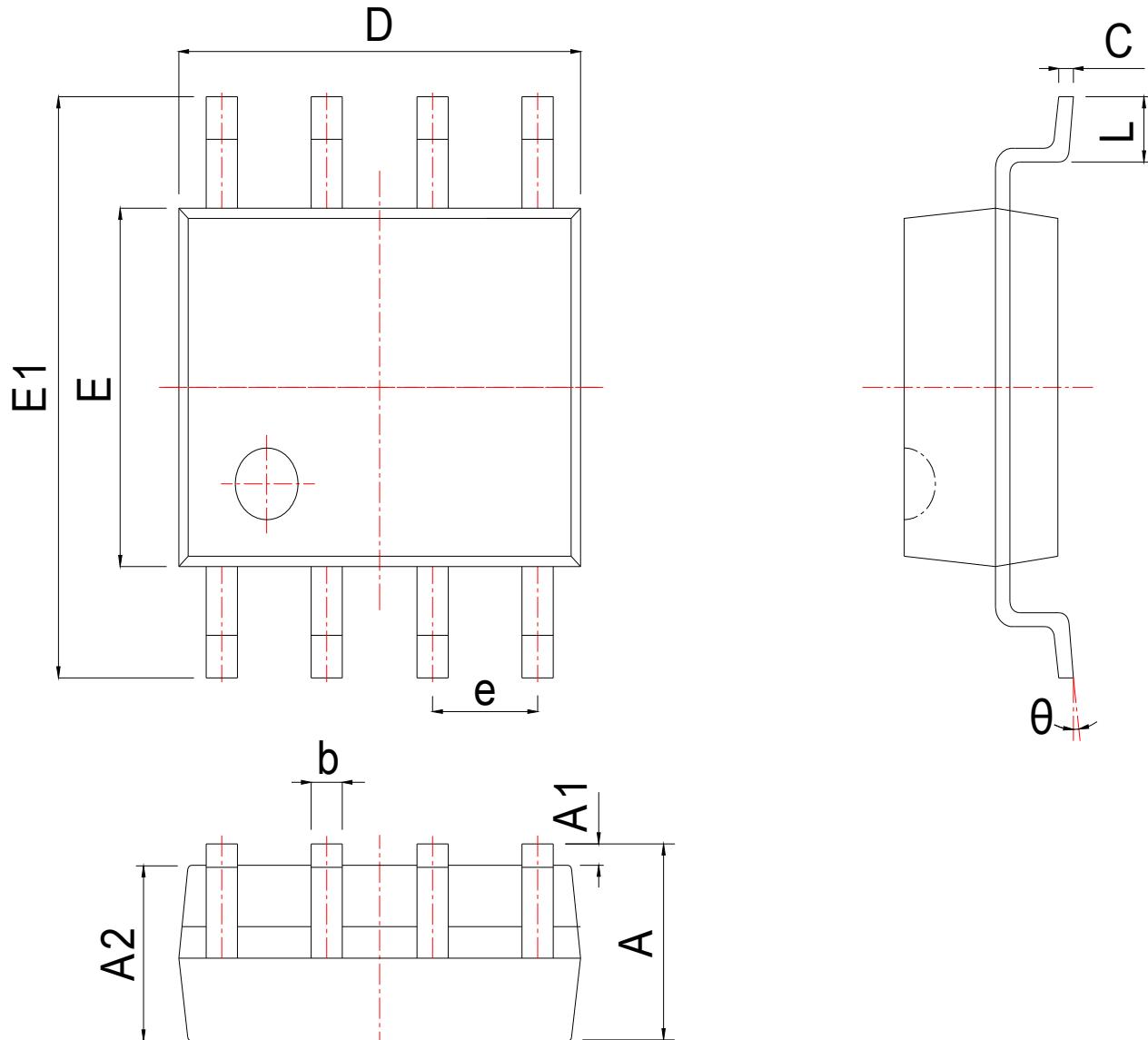
XXX =Lot number.

## Typical Characteristics



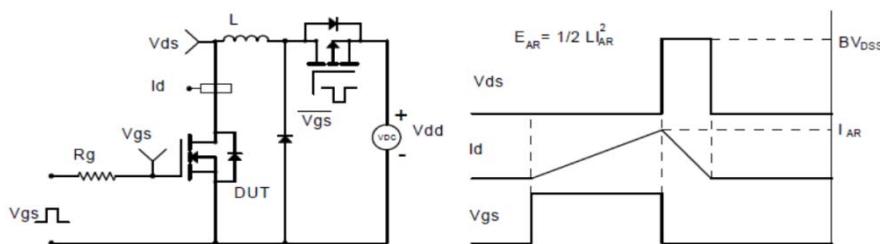
## Typical Characteristics



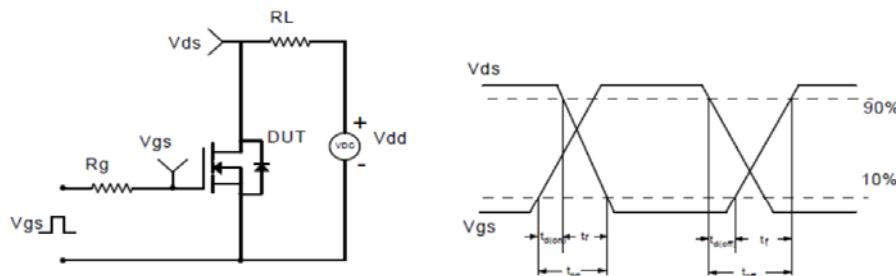
**Package Information**
**SOP8**


| SYMBOL   | MM        |       |           | INCH      |       |           |
|----------|-----------|-------|-----------|-----------|-------|-----------|
|          | MIN       | NOM   | MAX       | MIN       | NOM   | MAX       |
| A        | 1.300     | 1.525 | 1.750     | 0.051     | 0.060 | 0.069     |
| A1       | 0.050     | 0.150 | 0.250     | 0.002     | 0.006 | 0.010     |
| A2       | 1.350     | 1.450 | 1.550     | 0.053     | 0.057 | 0.061     |
| b        | 0.330     | 0.420 | 0.510     | 0.013     | 0.017 | 0.020     |
| c        | 0.170     | 0.210 | 0.250     | 0.007     | 0.008 | 0.010     |
| D        | 4.700     | 4.900 | 5.100     | 0.185     | 0.193 | 0.201     |
| E        | 3.800     | 3.900 | 4.000     | 0.150     | 0.154 | 0.157     |
| E1       | 5.800     | 6.000 | 6.200     | 0.228     | 0.236 | 0.244     |
| e        | 1.270 BSC |       |           | 0.050 BSC |       |           |
| L        | 0.400     | 0.835 | 1.270     | 0.016     | 0.033 | 0.050     |
| $\theta$ | $0^\circ$ |       | $8^\circ$ | $0^\circ$ |       | $8^\circ$ |

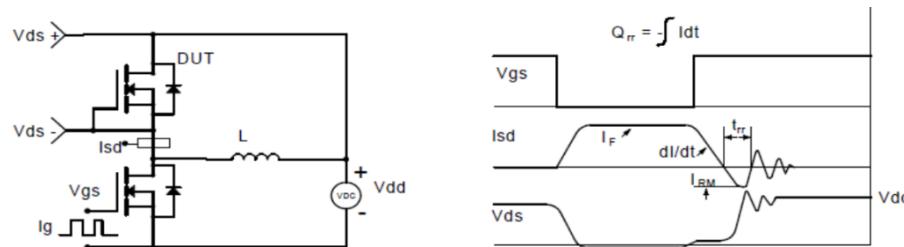
### Avalanche Test Circuit and Waveforms



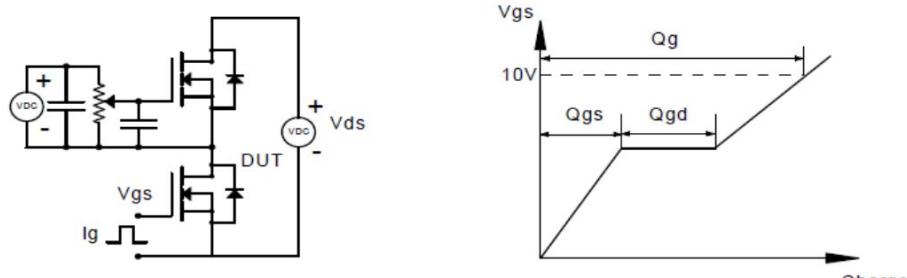
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



### Customer Service

Kwansemi Semiconductor Co.,Ltd

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Web:[www.kwansemi.com](http://www.kwansemi.com)

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